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(54) **ULTRASONIC DEVICE, ULTRASONIC PROBE, ELECTRONIC EQUIPMENT, AND ULTRASONIC IMAGE DEVICE**

H01L 41/332; H01L 41/081; H01L 41/053; A61B 8/4488; A61B 8/4427; A61B 8/14; A61B 8/00

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See application file for complete search history.

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H01L 41/08 (2006.01)
H01L 27/20 (2006.01)
B06B 1/06 (2006.01)

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(58) **Field of Classification Search**

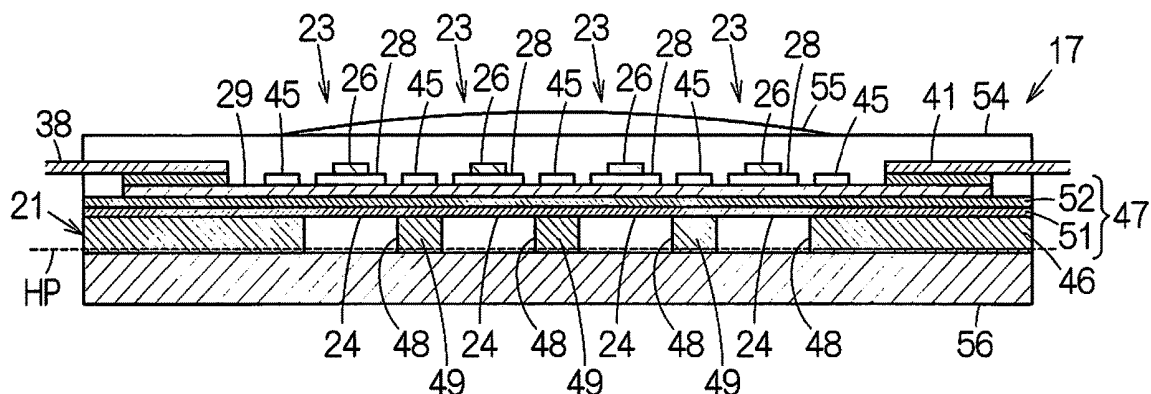
CPC B06B 1/0629; B06B 1/06; H01L 27/20;

(57)

ABSTRACT

An ultrasonic device includes a base, a plurality of ultrasonic transducer elements, and a reinforcing body. The base defines a plurality of openings arranged in an array form. The ultrasonic transducer elements are arranged respectively corresponding to the openings with a plurality of vibration films being respectively provided for the ultrasonic transducer elements. The reinforcing body is fixed to the base in an area between adjacent ones of the vibration films when viewed in a plan view along a thickness direction of the base. The reinforcing body has Young's modulus greater than Young's modulus of the base.

16 Claims, 10 Drawing Sheets



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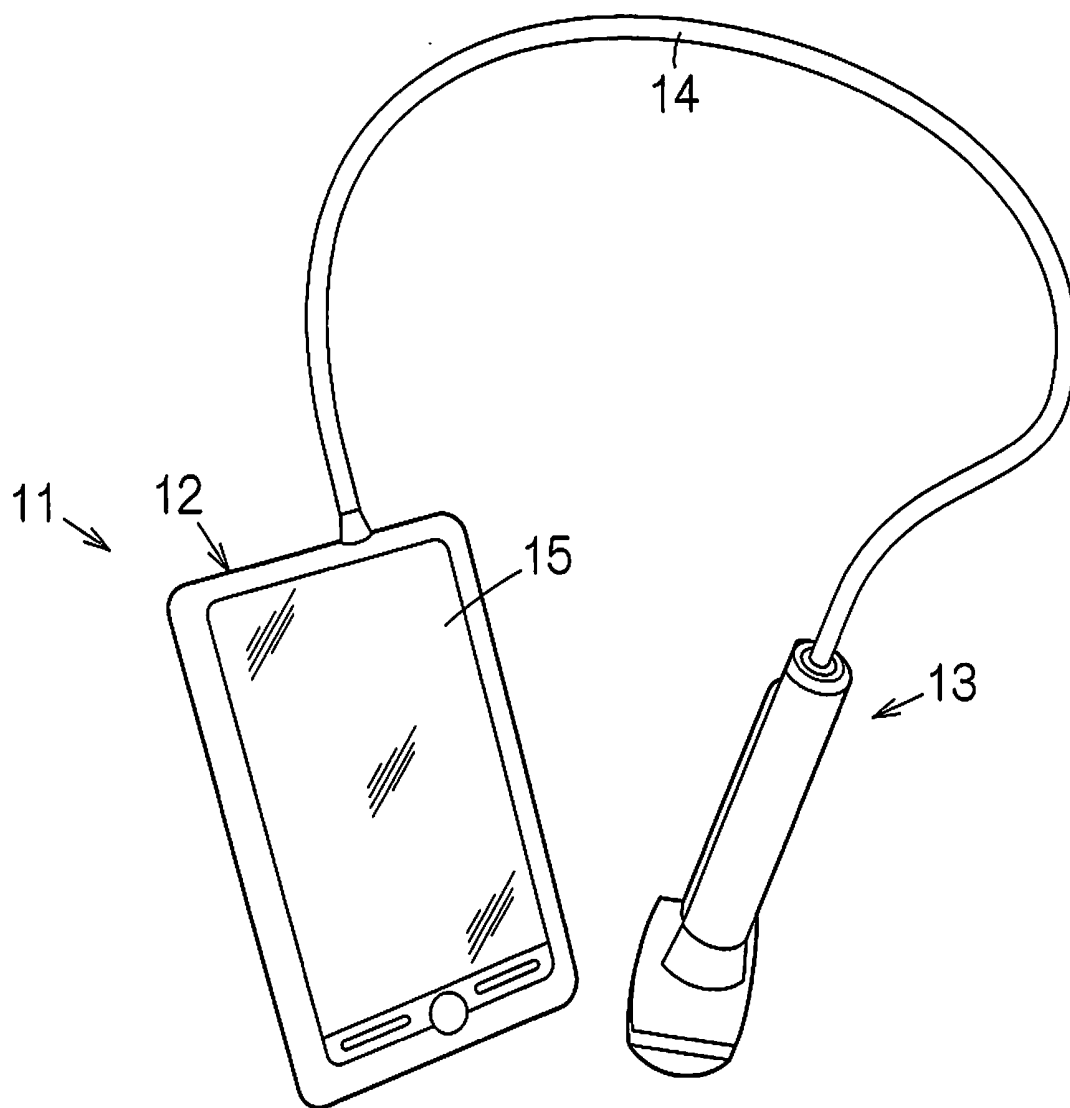
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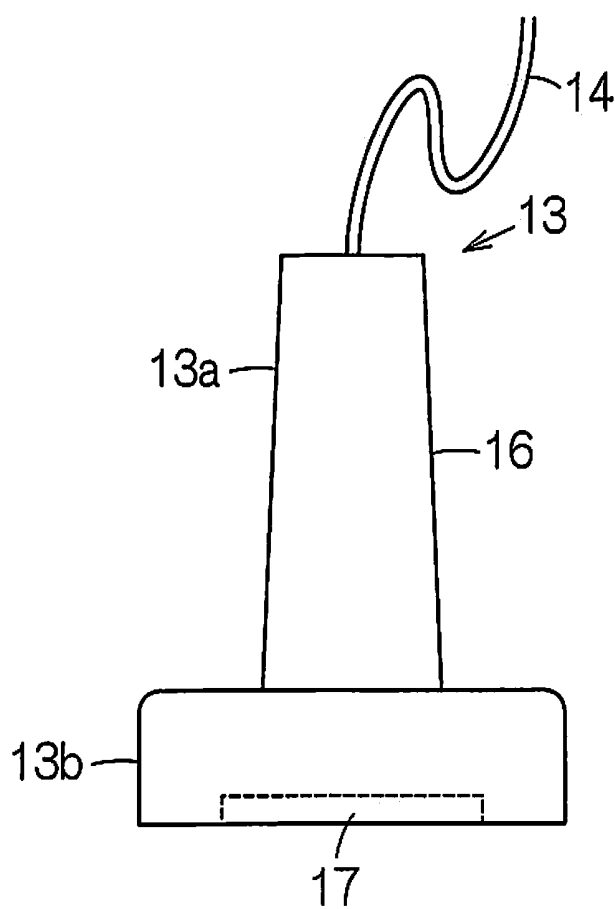
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**Fig. 1**

**Fig. 2**

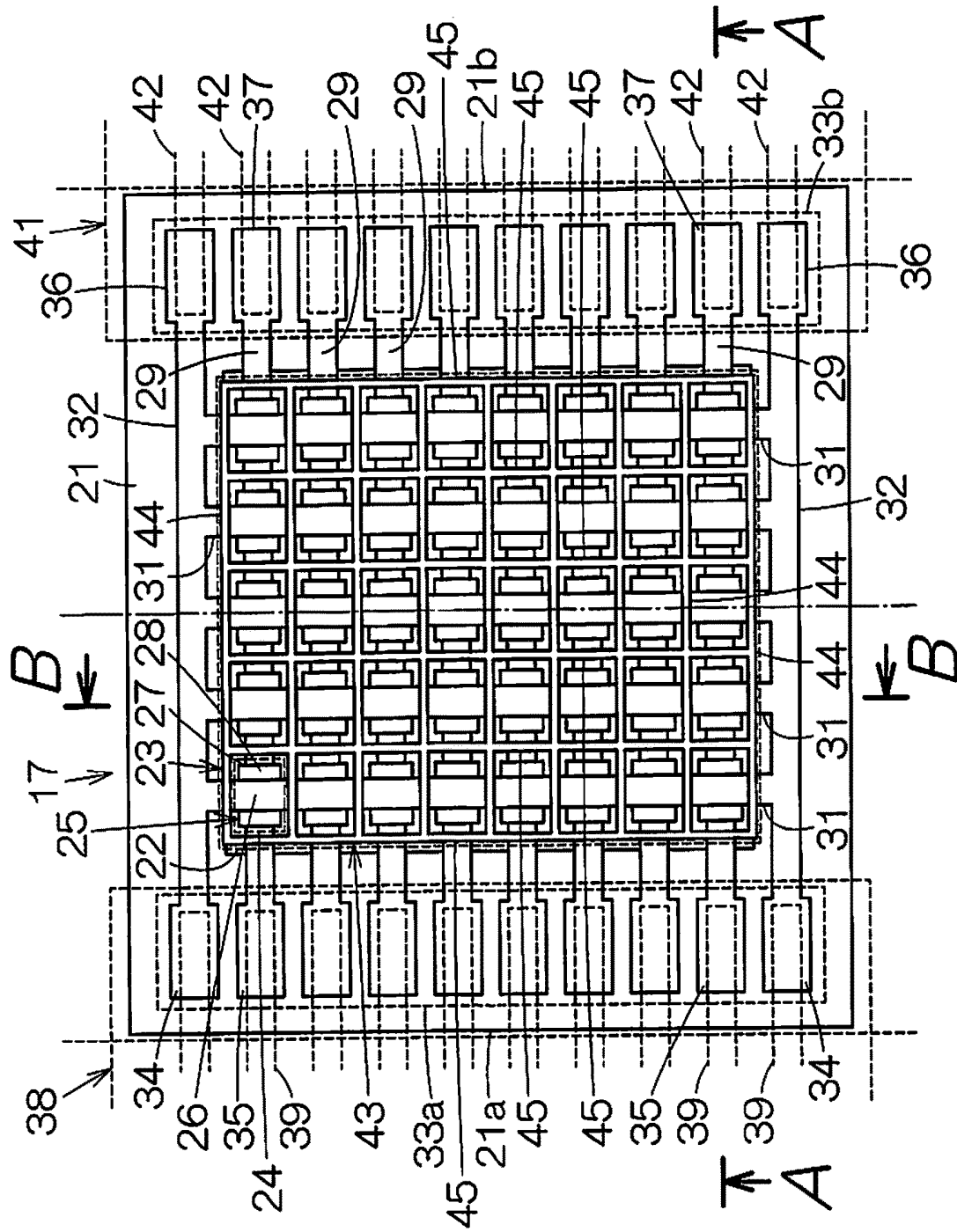


Fig. 3

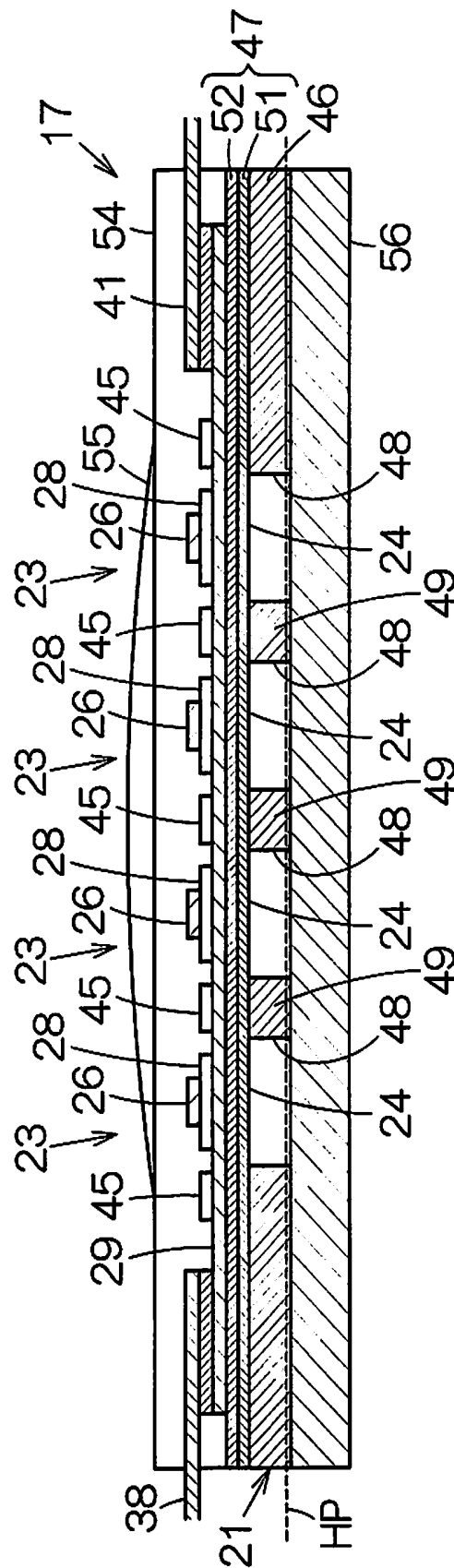


Fig. 4

Fig. 5

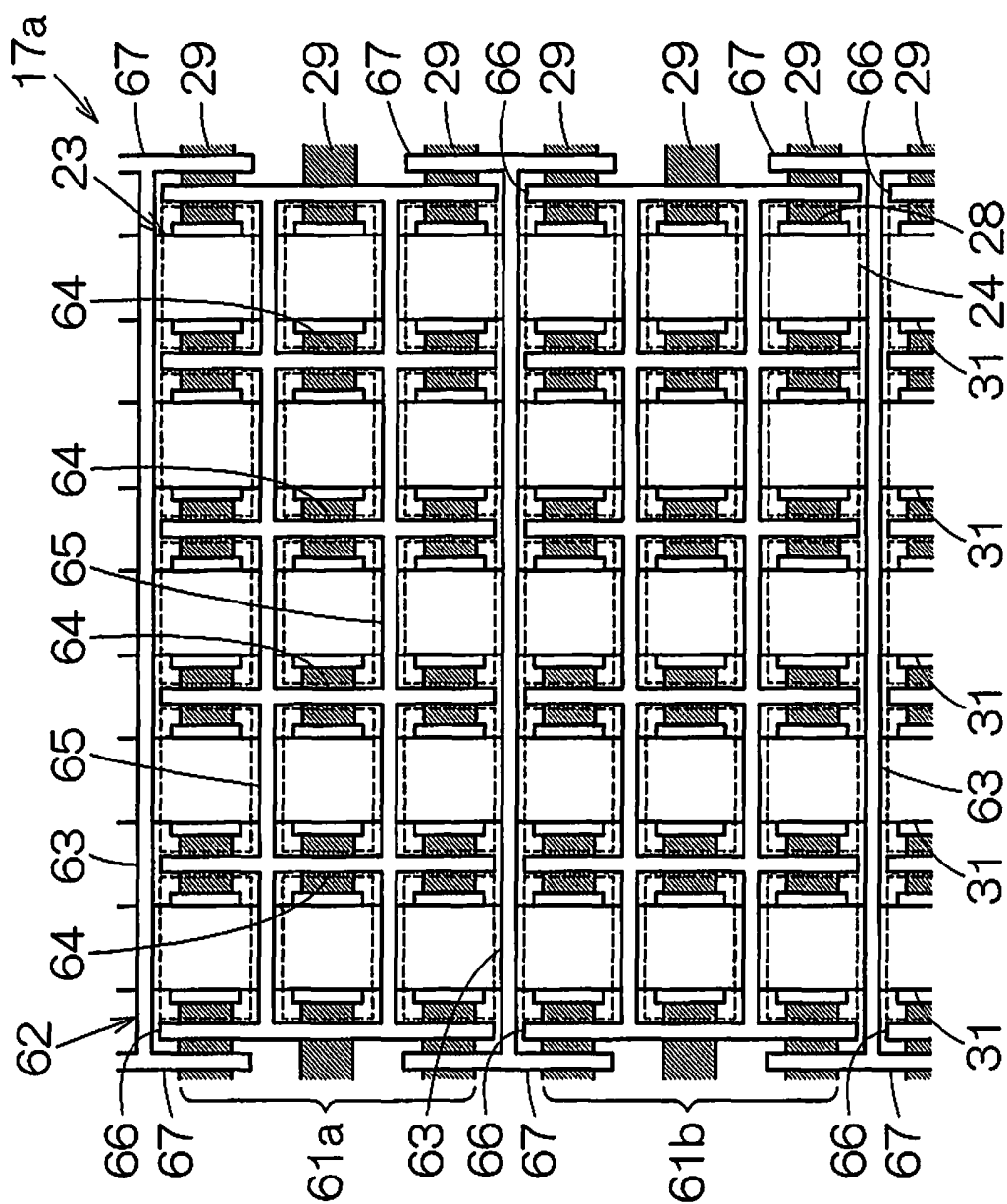


Fig. 6

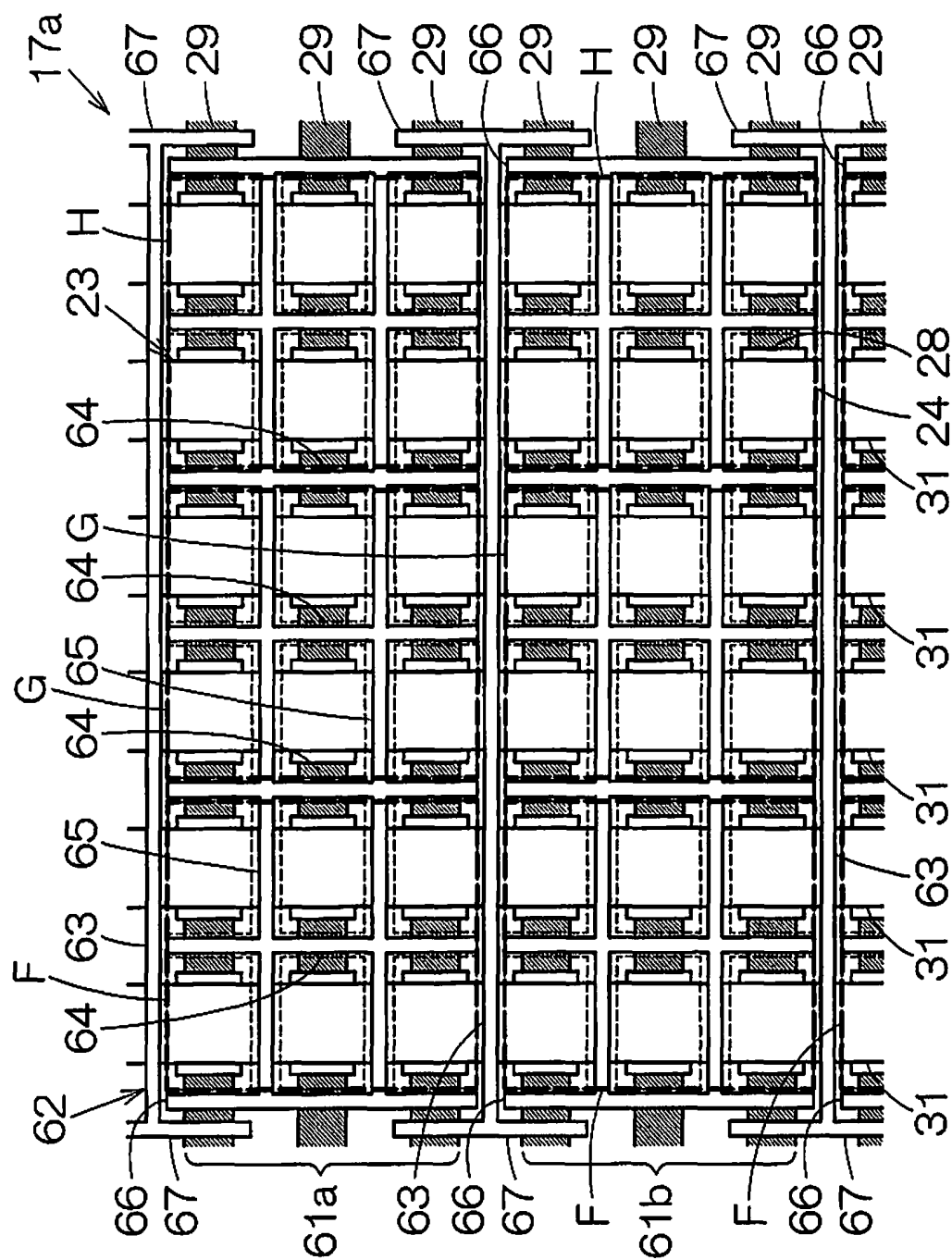


Fig. 7

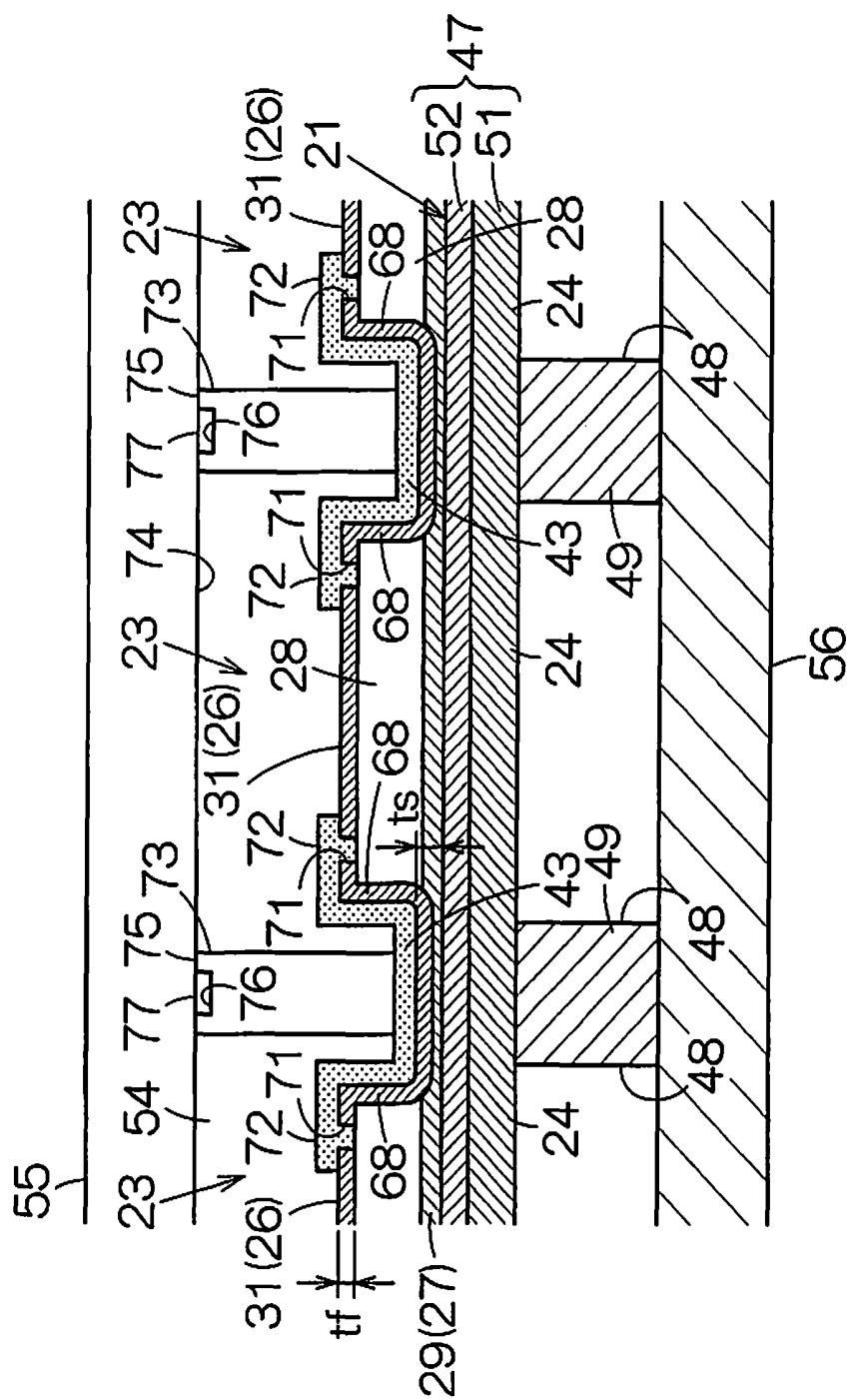


Fig. 8

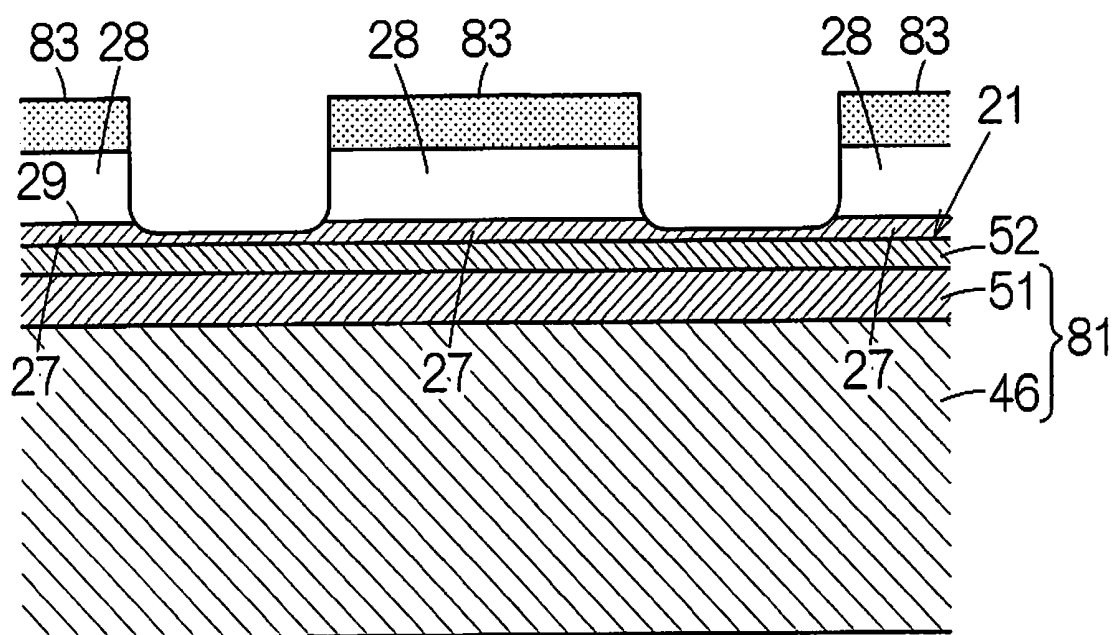


Fig. 9

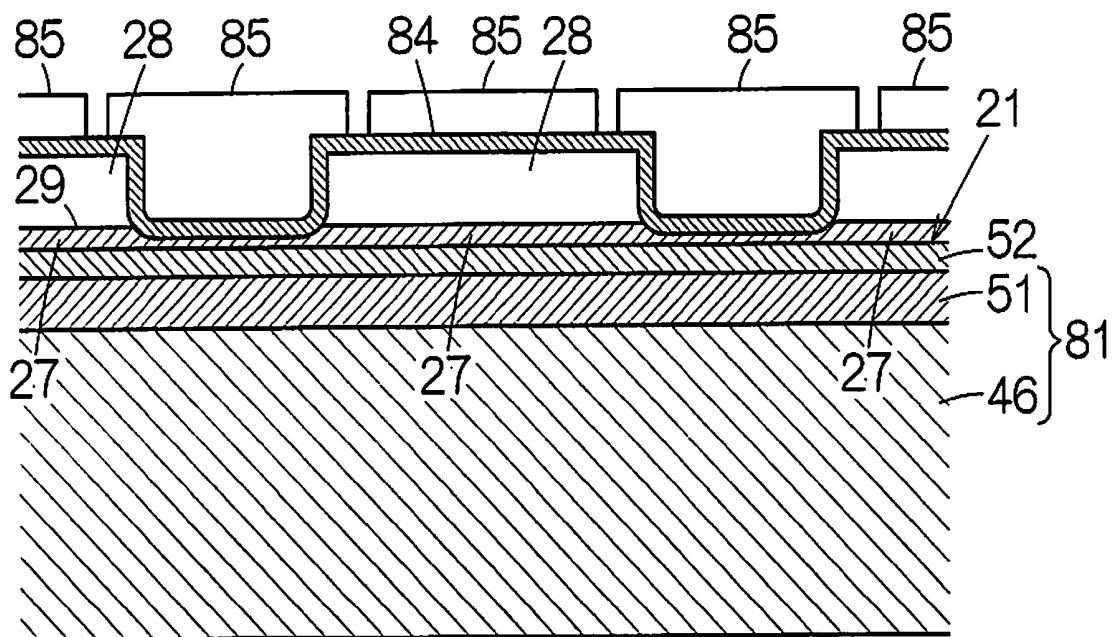


Fig. 10

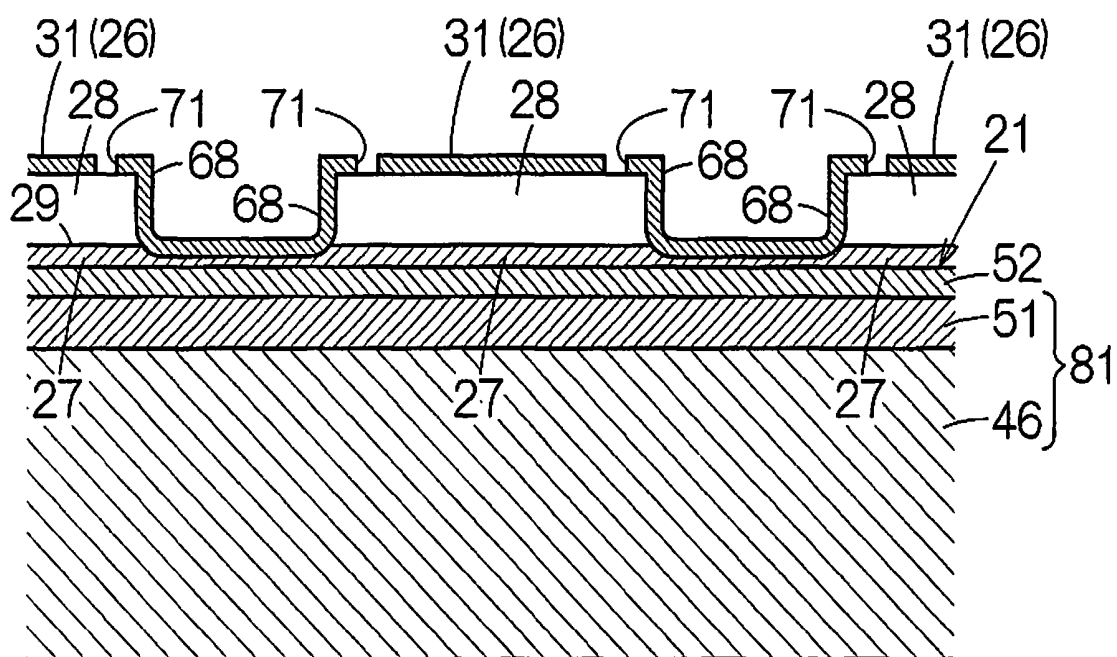


Fig. 11

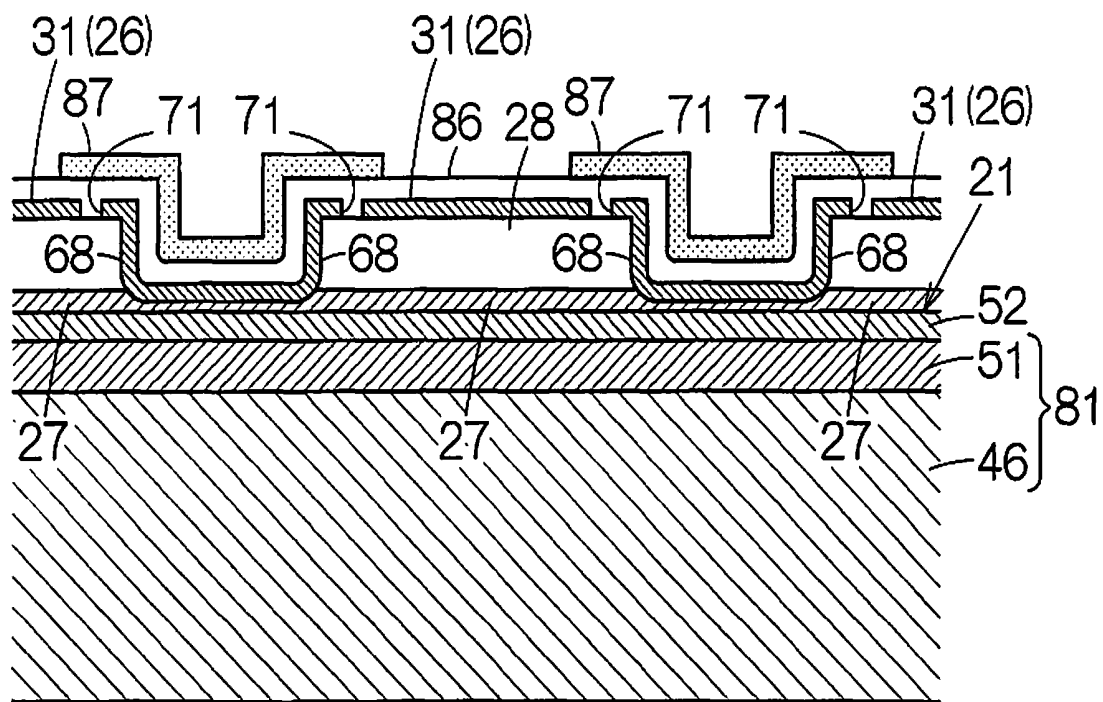


Fig. 12

ULTRASONIC DEVICE, ULTRASONIC PROBE, ELECTRONIC EQUIPMENT, AND ULTRASONIC IMAGE DEVICE

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims priority to Japanese Patent Application No. 2013-203476 filed on Sep. 30, 2013. The entire disclosure of Japanese Patent Application No. 2013-203476 is hereby incorporated herein by reference.

BACKGROUND

1. Technical Field

The present invention relates to an ultrasonic device, ultrasonic probe, electronic equipment, and ultrasonic image device or the like using the same.

2. Related Art

Ultrasonic devices are generally known. For example, with the ultrasonic device noted in Japanese Laid-Open Patent Publication No. 2005-51688, a base has a plurality of openings. The openings are arranged in array form. An ultrasonic transducer element is arranged for each opening. Each ultrasonic transducer element has a vibration film. A piezoelectric body and electrode are formed on the vibration film. Ultrasonic waves are emitted according to the ultrasonic vibration of the vibration film.

SUMMARY

Crosstalk of the ultrasonic waves occurs during ultrasonic vibration of the vibration films. The ultrasonic vibration of the vibration film is conveyed through the base and propagated in the adjacent vibration films. For preventing this kind of crosstalk, for example with Japanese Laid-Open Patent Publication No. 2007-235795, the piezoelectric body is segmented. However, when segmenting between vibration films with the ultrasonic device noted in Japanese Laid-Open Patent Publication No. 2005-51688, there is a marked weakening of support strength of the vibration film. If trying to ensure support strength, it is difficult to have higher density of the ultrasonic transducer elements.

With at least one aspect of the present invention, it is possible to provide an ultrasonic device for which it is possible to prevent crosstalk well by making the base strength great while realizing higher density of the ultrasonic transducer elements.

(1) An ultrasonic device according to one aspect includes a base, a plurality of ultrasonic transducer elements, and a reinforcing body. The base defines a plurality of openings arranged in an array form. The ultrasonic transducer elements are arranged respectively corresponding to the openings with a plurality of vibration films being respectively provided for the ultrasonic transducer elements. The reinforcing body is fixed to the base in an area between adjacent ones of the vibration films when viewed in a plan view along a thickness direction of the base. The reinforcing body has Young's modulus greater than Young's modulus of the base.

When sending ultrasonic waves, the vibration film of the ultrasonic transducer element does ultrasonic vibration. Ultrasonic wave signals are emitted according to the ultrasonic vibration. At this time, the base forms a frame body enclosing the opening for each individual opening. A reinforcing body is overlapped on the frame body to form a composite body. The bending rigidity of the composite body exceeds the bending rigidity of the frame body alone. The

rigidity of the frame body is increased. Wobbling of the frame body during ultrasonic vibration of the vibration film is suppressed. In this way, crosstalk of ultrasonic waves during ultrasonic vibration of one vibration film is prevented. As a result, it is possible for the ultrasonic transducer elements to be arranged at high density. On the other hand, when the frame body rigidity is low, there is distortion of the frame body during ultrasonic vibration of the vibration film, and crosstalk of the ultrasonic waves from one vibration film toward the adjacent vibration films occurs.

(2) The reinforcing body, in cooperation with the base, preferably forms a composite body having a second moment of area greater than a second moment of area of the base alone. The bending rigidity is specified by the product of the Young's modulus and the second moment of area. If the second moment of area of the composite body is greater than the second moment of area of the base alone, the bending rigidity will increase. The reinforcing body is able to effectively reinforce the bending rigidity.

(3) The reinforcing body preferably has a crossing part along a first direction and a second direction that cross each other in the plan view. The rigidity of the reinforcing body is increased by the reinforcing bodies crossing each other. The bending rigidity of the base is further increased.

(4) A crossing angle of the first direction and the second direction is preferably 90 degrees. The bending rigidity of the base is reliably increased.

(5) In the plan view, the reinforcing body preferably has a first straight line part cutting across an array area of the ultrasonic transducer elements in the first direction. In this way, the base rigidity is increased for the entire array area.

(6) The reinforcing body preferably has an additional crossing part spaced apart from the crossing part in the second direction for each group of the ultrasonic transducer elements connected in common to one signal line among the ultrasonic transducer elements. The vibration films belonging to the group of ultrasonic transducer elements connected in common to one signal line vibrate simultaneously according to the supply of drive signals. The group of ultrasonic transducer elements that vibrate simultaneously forms one segment. The reinforcing body is interrupted for each segment, so transmission of the ultrasonic vibration between segments by conveyance through the reinforcing body is prevented. Ultrasonic wave crosstalk is reduced.

(7) The reinforcing body preferably further includes a first straight line part positioned in an area between the crossing part and the additional crossing part in the plan view, and an auxiliary reinforcing body part extending along the second direction. Even when the reinforcing body is segmented, the segmented area is reinforced by the auxiliary reinforcing body part. Despite segmenting of the reinforcing body, rigidity is ensured by the work of the auxiliary reinforcing body part.

(8) The reinforcing body preferably has a second straight line part cutting across the array area of the ultrasonic transducer elements in the second direction in the plan view. In this way, the rigidity of the base is increased for the entire array area.

(9) The reinforcing body preferably has an additional crossing part spaced apart from the crossing part in the first direction for each group of the ultrasonic transducer elements connected in common to one signal line among the ultrasonic transducer elements. The vibration films belonging to the group of ultrasonic transducer elements connected in common to one signal line vibrate simultaneously according to the supply of drive signals. The group of ultrasonic transducer elements vibrating simultaneously forms one

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segment. Since the reinforcing body is interrupted for each segment, the transmission of ultrasonic vibration between segments conveyed through the reinforcing body is prevented. Crosstalk of ultrasonic waves is reduced. The segments are arranged in array form.

(10) The ultrasonic device preferably further includes: a first conductive film extending in a first direction in common to the ultrasonic transducer elements; a piezoelectric film disposed on the first conductive film for each of the ultrasonic transducer elements; a second conductive film extending in a second direction in common to the ultrasonic transducer elements; and an insulating film separating the first conductive film from the second conductive film on the piezoelectric film, the insulating film being continuous from the reinforcing body. The reinforcing body is preferably made of an insulating material. The first conductive film and the second conductive film are mutually separated on the piezoelectric film. A space in contact with the piezoelectric film is formed between the first conductive film and the second conductive film on the surface of the piezoelectric film. The space is occupied by the insulating film. The insulating film prevents the entry of moisture into the space. As a result, even if the ultrasonic device is exposed to moisture, it is possible to avoid electrical shorting between the first conductive film and the second conductive film.

(11) The ultrasonic device preferably further includes an additional second conductive film extending in the second direction. The first conductive film preferably has a film thickness greater than a film thickness of the second conductive film between the second conductive film and the additional second conductive film. Since sufficient film thickness is ensured for the first conductive film, it is possible to avoid an increase in wiring resistance. Therefore, it is possible to sufficiently ensure ultrasonic wave detection sensitivity.

(12) It is possible to use the ultrasonic device incorporated in a probe. The probe can be equipped with the ultrasonic device, and a case supporting the ultrasonic device.

(13) It is possible to use the ultrasonic device incorporated in electronic equipment. The electronic equipment can be equipped with the ultrasonic device, and a processing device connected to the ultrasonic device, and configured to process the output of the ultrasonic device.

(14) It is possible to use the ultrasonic device incorporated in an ultrasonic image device. The ultrasonic image device can be equipped with the ultrasonic device, and a display device configured to display an image generated based on the output of the ultrasonic device.

BRIEF DESCRIPTION OF THE DRAWINGS

Referring now to the attached drawings which form a part of this original disclosure:

FIG. 1 is an external view schematically showing an ultrasonic diagnostic device as an example of an electronic equipment.

FIG. 2 is an enlarged front view of the ultrasonic probe.

FIG. 3 is an enlarged plan view of the ultrasonic transducer element unit of the first embodiment.

FIG. 4 is a cross section view along line A-A of FIG. 3.

FIG. 5 is a partially enlarged cross section view along line B-B of FIG. 3.

FIG. 6 is an enlarged partial plan view of the ultrasonic transducer element unit of the second embodiment, correlating to a partial enlarged view of FIG. 3.

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FIG. 7 is an enlarged partial plan view of the ultrasonic transducer element unit of a modification example of the second embodiment, correlating to the partial enlarged view of FIG. 3.

FIG. 8 is an enlarged partial cross section view of the ultrasonic transducer element unit of the third embodiment, correlating to the partial enlarged view of FIG. 4.

FIG. 9 is a drawing schematically showing the piezoelectric film forming process which is part of the manufacturing method of the ultrasonic transducer element unit.

FIG. 10 is a drawing schematically showing the raw material layer forming process which is part of the manufacturing method of the ultrasonic transducer element unit.

FIG. 11 is a drawing schematically showing the second conductive film forming process which is part of the manufacturing method of the ultrasonic transducer element unit.

FIG. 12 is a drawing schematically showing the reinforcing body forming process which is part of the manufacturing method of the ultrasonic transducer element unit.

DETAILED DESCRIPTION OF EXEMPLARY EMBODIMENTS

Hereafter, an embodiment of the present invention while referring to the attached drawings will be described. This embodiment described hereafter does not unduly limit the contents of the present invention noted in the scope of patent claims, and all of the structures described with this embodiment are not absolutely necessary as means for solving of the present invention.

(1) Overall Configuration of the Ultrasonic Diagnostic Device

FIG. 1 schematically shows a specific example of electronic equipment, specifically, the configuration of an ultrasonic diagnostic device (ultrasonic image device) 11. The ultrasonic diagnostic device 11 is equipped with a device terminal (processing device) 12 and an ultrasonic probe (probe) 13. The device terminal 12 and the ultrasonic probe 13 are connected to each other by a cable 14. The device terminal 12 and the ultrasonic probe 13 exchange electronic signals through the cable 14. A display panel (display device) 15 is incorporated in the device terminal 12. The screen of the display panel 15 is exposed on the surface of the device terminal 12. With the device terminal 12, an image is generated based on the ultrasonic waves detected by the ultrasonic probe 13. The detected results put into image form are displayed on the screen of the display panel 15.

As shown in FIG. 2, the ultrasonic probe 13 has a case 16. Inside the case 16 is housed an ultrasonic transducer element unit (hereafter called "element unit") 17. The surface of the element unit (ultrasonic device) 17 can be exposed on the surface of the case 16. The element unit 17 outputs ultrasonic waves from the surface and receives reflected waves of the ultrasonic waves. In addition, the ultrasonic probe 13 can be equipped with a probe head 13b linked so as to be feely detachable with a probe main unit 13a. At this time, the element unit 17 can be incorporated inside the case 16 of the probe head 13b.

FIG. 3 schematically shows a plan view of the element unit 17 of the first embodiment. The element unit 17 is equipped with a base 21. An element array 22 is formed on the base 21. The element array 22 is constituted with an array of ultrasonic transducer elements (hereafter called "elements") 23. The array is formed in a matrix of a plurality

of columns and a plurality of rows. In addition, it is possible to establish a zigzag arrangement for the array. With a zigzag arrangement, the even numbered Xrow element **23** group can be skewed by a column pitch of $\frac{1}{2}$ in relation to the odd numbered Xrow element **23** group. The number of elements of one of the odd numbered Xrow and the even numbered Xrow can be one less than the number of elements of the other.

Each individual element **23** is equipped with a vibration film **24**. Details of the vibration film **24** will be described later. FIG. 3 depicts the outline of the vibration film **24** with a dotted line with a plan view in the direction orthogonal to the film surface of the vibration film **24** (substrate thickness direction plan view). The inner side of the outline correlates to the interior of the area of the vibration film **24**. The outside of the outline correlates to outside the area of the vibration film **24**. A piezoelectric element **25** is formed on the top of the vibration film **24**. As described later, with the piezoelectric element **25**, a piezoelectric film **28** is sandwiched between an upper electrode **26** and a lower electrode **27**. These are overlapped in sequence. The element unit **17** is constituted as one ultrasonic transducer element chip.

A plurality of first conductive films **29** are formed on the surface of the base **21**. The first conductive films **29** extend mutually in parallel to the Xrow direction of the array. One first conductive film **29** is allocated per Xrow of elements **23**. One first conductive film **29** is arranged in common with elements **23** aligned in the Xrow direction of the array. The first conductive film **29** has the lower electrode **27** formed for each individual element **23**. In this way, the first conductive film **29** is arranged both inside the area and outside the area of the vibration film **24**. For example, titanium (Ti), iridium (Ir), or a laminated film of titanium (Ti) and platinum (Pt) can be used for the first conductive film **29**. However, it is also possible to use other conductive materials for the first conductive film **29**.

A plurality of second conductive films **31** are formed on the surface of the base **21**. The second conductive films **31** extend mutually in parallel to the column direction of the array. One second conductive film **31** is allocated for each column of elements **23**. One second conductive film **31** is connected in common to elements **23** aligned in the column direction of the array. The second conductive film **31** has the upper electrode **26** formed for each individual element **23**. Both ends of the second conductive film **31** are respectively connected to a pair of lead-out wires **32**. The lead-out wires **32** extend mutually in parallel in the row direction of the array. Therefore, all of the second conductive films **31** have the same length. In this way, the upper electrodes **26** are connected in common to the elements **23** of the entire matrix. In this way, the second conductive films **31** are arranged on the inside area and outside area of the vibration film **24**. The second conductive films **31** can be formed using iridium (Ir), for example. Other conductors can also be used for the second conductive films **31**.

The energization of the elements **23** can be switched for each Xrow. Linear scanning or sector scanning is realized according to this energization switching. Since one Xrow of elements **23** output ultrasonic waves simultaneously, it is possible to determine the number of the elements **23** in one row, in other words, the number of columns of the array, according to the ultrasonic wave output level. The number of columns can be set to approximately 10 to 15 columns, for example. This is abbreviated in the drawing with five columns depicted. The number of Xrows of the array can be determined according to the expansion of the scan range. The number of Xrows can be set to 128 Xrows or 256

Xrows, for example. This is abbreviated in the drawing with eight Xrows depicted. The role of the upper electrodes **26** and the lower electrodes **27** can also be interchanged. Specifically, while the lower electrodes are connected in common to the elements **23** of the entire matrix, the upper electrodes can be connected in common to each Xrow of the array.

The outline of the base **21** has a first side **21a** and a second side **21b** facing opposite, partitioned by a pair of straight lines that are mutually parallel. One line of first terminal arrays **33a** is arranged between the first side **21a** and the element array **22** outline. One line of second terminal arrays **33b** is arranged between the second side **21b** and the element array **22** outline. The first terminal arrays **33a** can be formed in one line in parallel to the first side **21a**. The second terminal arrays **33b** can be formed in one line in parallel to the second side **21b**. The first terminal array **33a** is constituted by one pair of upper electrode terminals **34** and a plurality of lower electrode terminals **35**. Similarly, the second terminal array **33b** is constituted by a pair of upper electrode terminals **36** and a plurality of lower electrode terminals **37**. The upper electrode terminals **34** and **36** are respectively connected to both ends of one lead-out wire **32**. The lead-out wire **32** and the upper electrode terminals **34** and **36** can be formed plane-symmetrically at the perpendicular plane that bisects the element array **22**. The lower electrode terminals **35** and **37** are respectively connected to both ends of one second conductive film **31**. The second conductive film **31** and the lower electrode terminals **35** and **37** can be formed plane-symmetrically at the perpendicular plane that bisects the element array **22**. Here, the outline of the base **21** is formed as a rectangle. The outline of the base **21** can also be square or can be a trapezoid.

A first flexible printed wiring board (hereafter called "first wiring board") **38** is coupled to the base **21**. The first wiring board **38** is covered by the first terminal array **33a**. A conductive line, specifically a first signal line **39**, corresponding individually to the upper electrode terminal **34** and the lower electrode terminal **35**, is formed on one end of the first wiring board **38**. The first signal line **39** is bonded separately facing to individually match the upper electrode terminal **34** and the lower electrode terminal **35**. Similarly, a second flexible printed wiring board (hereafter called "second wiring board") **41** is covered on the base **21**. The second wiring board **41** is covered by the second terminal array **33b**. A conductive line, specifically, a second signal line **42**, is formed corresponding individually to the upper electrode terminal **36** and the lower electrode terminal **37** at one end of the second wiring board **41**. The second signal line **42** is bonded separately facing to individually match the upper electrode terminal **36** and the lower electrode terminal **37**.

A grid form reinforcing body **43** is fixed on the surface of the base **21**. The reinforcing body **43** is overlapped on the surface of the base **21**. The reinforcing body **43** is equipped with a plurality of first elongated pieces (first straight line parts) **44** extending in the Xrow direction of the element array **22** (first direction), and a plurality of second elongated pieces (second straight line parts) **45** extending in the column direction of the element array **22** (second direction). Each of the first elongated pieces **44** has a shape that cuts across the area of the element array **22** completely in the Xrow direction. Each of the second elongated pieces **45** has a shape that cuts across the area of the element array **22** completely in the column direction. The first elongated pieces **44** and the second elongated pieces **45** form a crossing part crossing each other at a crossing angle of 90

degrees. The first elongated pieces **44** are arranged in parallel to each other. The second elongated pieces **45** are arranged in parallel to each other. The first elongated pieces **44** and the second elongated pieces **45** are arranged at positions skewed from the elements **23** in the parallel direction to the surface of the base **21**. One Xrow of the elements **23** are arranged between adjacent first elongated pieces **44**. One column of the elements **23** are arranged between adjacent second elongated pieces **45**. The reinforcing body **43** is formed from an insulating material such as alumina (Al_2O_3) or zirconium oxide (ZrO_2) for example. The alumina or zirconium oxide has a greater Young's modulus than that of silicon or silicon oxide. The reinforcing body **43** can be formed using photolithography technology, for example.

As shown in FIG. 4, the base **21** is equipped with a main unit **46** and a flexible film **47**. The flexible film **47** is formed over the entire surface on the surface of the main unit **46**. The main unit **46** is formed from silicon (Si), for example. An opening **48** is formed on each individual element **23** on the main unit **46**. The openings **48** are arranged in array form on the main unit **46**. The outline of the area in which the openings **48** are arranged correlates to the outline of the element array **22**. A partition wall **49** is demarcated between two adjacent openings **48**. Adjacent openings **48** are partitioned by the partition wall **49**. The wall thickness of the partition wall **49** correlates to the gap between the openings **48**. The partition wall **49** defines two wall surfaces within the plane mutually expanding in parallel. The wall thickness correlates to the distance between two wall surfaces. Specifically, the wall thickness can be regulated by the length of the perpendicular line sandwiched between the wall surfaces orthogonal to the wall surface.

The flexible film **47** is constituted by a silicon oxide (SiO_2) layer **51** laminated on the surface of the main unit **46**, and a zirconium oxide (ZrO_2) layer **52** laminated on the surface of the silicon oxide layer **51**. The flexible film **47** is in contact with the opening **48**. In this way, a portion of the flexible film **47** corresponding to the outline of the opening **48** forms the vibration film **24**. Of the flexible film **47**, the vibration film **24** is the part for which it is possible to do film vibration in the thickness direction of the main unit **46** since it faces the opening **48**. The film thickness of the silicon oxide layer **51** can be determined based on the resonance frequency.

The reinforcing body **43** (second elongated piece **45**) is overlapped on the surface of the flexible film **47** on the partition wall **49**. The second elongated piece **45** is overlapped on the partition wall **49** that functions as a girder or beam to form a composite body. Depending on the overlapping, the composite body can have a second moment of area (a moment of inertia of plane area) greater than the second moment of area of the base **21** alone. Here, with the composite body, the bending rigidity is increased in the direction orthogonal to the surface of the base **21**.

On the surface of the vibration film **24** are laminated in sequence the first conductive film **29**, the piezoelectric film **28**, and the second conductive film **31**. The piezoelectric film **28** can be formed using lead zircon titanate (PZT), for example. It is also possible to use another piezoelectric material for the piezoelectric film **28**. The piezoelectric film **28** covers at least a portion of the lower electrode **27** and a portion of the vibration film **24**. The upper electrode **26** covers at least a portion of the piezoelectric film **28**. Here, the piezoelectric film **28** completely covers the surface of the first conductive film **29** below the second conductive film **31**. It is possible to avoid shorting between the first con-

ductive film **29** and the second conductive film **31** by working of the piezoelectric film **28**.

An acoustic adjustment layer **54** is laminated on the surface of the base **21**. The acoustic adjustment layer **54** can be cover the surface of the base **21** over the entire surface, for example. As a result, the element array **22**, the first and second terminal arrays **33a** and **33b**, and the first and second wiring boards **38** and **41** are covered by the acoustic adjustment layer **54**. The acoustic adjustment layer **54** is adhered to the surface of the element **23**. It is possible to use a silicone resin film for the acoustic adjustment layer **54**, for example. The acoustic adjustment layer **54** protects the element array **22** structure, the first terminal array **33a** and the first wiring board **38** junction, and the second terminal array **33b** and the second wiring board **41** junction.

An acoustic lens **55** is laminated on the acoustic adjustment layer **54**. The acoustic lens **55** is adhered to the surface of the acoustic adjustment layer **54**. The outer surface of the acoustic lens **55** is formed with a partial cylindrical surface. The partial cylindrical surface has a generatrix parallel to the second conductive film **31**. The curvature of the partial cylindrical surface is determined according to the focal position of the ultrasonic waves emitted from one Xrow of elements **23** connected to one line of the first conductive films **29**. The acoustic lens **55** is formed from silicone resin, for example.

A reinforcing plate **56** is fixed to the back surface of the base **21**. The back surface of the base **21** is overlapped on the front surface of the reinforcing plate **56**. The reinforcing plate **56** closes the openings **48** at the back surface of the element unit **17**. The reinforcing plate **56** can be equipped with a rigid base. The reinforcing plate **56** can be formed from a silicon substrate, for example. The plate thickness of the base **21** is set to approximately 100 μm , for example, and the plate thickness of the reinforcing plate **56** is set to approximately 100 to 150 μm , for example. Here, the partition wall **49** is bonded to the reinforcing plate **56**. The reinforcing plate **56** is bonded at a bonding area of at least one location on each partition wall **49**. An adhesive agent can be used for the bonding.

As shown in FIG. 5, the piezoelectric film **28** is covered on the first conductive film **29**. The piezoelectric film **28** contacts the surface of the vibration film **24** in a range expanding to the outside from the edge of the first conductive film **29**. The piezoelectric film **28** completely separates the first conductive film **29** and the second conductive film **31** from each other. This avoids a short between the first conductive film **29** and the second conductive film **31**.

The reinforcing body **43** (first elongated piece **44**) is overlapped on the surface of the flexible film **47** on the partition wall **49**. The first elongated piece **44** is overlapped on the partition wall **49** that functions as a girder to form a composite body. Depending on the overlapping, the composite body can have a second moment of area greater than the second moment of area of the base **21** alone. Here, with the composite body, the bending rigidity is increased in the direction orthogonal to the surface of the base **21**.

(2) Operation of the Ultrasonic Diagnostic Device

Next, a brief description of the operation of the ultrasonic diagnostic device **11** will be provided. For sending of ultrasonic waves, pulse signals are supplied to the piezoelectric element **25**. The pulse signals are supplied to the elements **23** for each Xrow through the lower electrode terminals **35** and **37** and the upper electrode terminals **34** and **36**. With each element **23**, an electric field acts on the

piezoelectric film 28 between the lower electrode 27 and the upper electrode 26. The piezoelectric film 28 vibrates with the ultrasonic waves. The vibration of the piezoelectric film 28 is conveyed to the vibration film 24. In this way, the vibration film 24 does ultrasonic vibration. As a result, the desired ultrasonic beams are emitted toward the subject (e.g. the interior of a human body).

The reflected waves of the ultrasonic waves vibrate the vibration film 24. The ultrasonic vibration of the vibration film 24 makes the piezoelectric film 28 do ultrasonic vibration at a desired frequency. Voltage is output from the piezoelectric element 25 according to the piezoelectric effect of the piezoelectric element 25. Electric potential is generated between the upper electrode 26 and the lower electrode 27 with each element 23. The electric potential is output as electric signals from the lower electrode terminals 35 and 37 and the upper electrode terminals 34 and 36. In this way, ultrasonic waves are detected.

The sending and receiving of ultrasonic waves is repeated. As a result, linear scanning or sector scanning is realized. When scanning is completed, an image is formed based on the digital signals of the output signals. The formed image is displayed on the screen of the display panel 15.

With the element unit 17, the partition wall 49 forms a frame body that encloses the opening 48 for each of the openings 48. The first elongated piece 44 and the second elongated piece 45 are overlapped on the frame body to form a composite body. The bending rigidity of the composite body exceeds the bending rigidity of the frame body alone. The rigidity of the frame body is increased. Wobbling of the frame body during ultrasonic vibration of the vibration film 24 is suppressed. In this way, crosstalk of ultrasonic waves during ultrasonic vibration of one vibration film 24 is prevented. When the frame body rigidity is low, there is distortion of the frame body during ultrasonic vibration of the vibration film 24, and crosstalk of the ultrasonic waves from one vibration film 24 toward the adjacent vibration films 24 occurs.

The bending rigidity is specified by the product of the Young's modulus and the second moment of area. As described previously, if the second moment of area of the composite body formed by the partition wall 49 and the reinforcing body 43 is greater than the second moment of area of the partition wall 49 alone, the bending rigidity will increase. The reinforcing body 43 is able to effectively reinforce the bending rigidity.

In particular, the first elongated pieces 44 and the second elongated pieces 45 cross each other extending in the row direction and the column direction mutually crossing each other. By the first elongated pieces 44 and the second elongated pieces 45 crossing in a T shape or a plus shape, the rigidity of the reinforcing body 43 and thus the composite body is increased. In this way, the bending rigidity of the base 21 is further increased. Furthermore, since the crossing angle of the first elongated piece 44 and the second elongated piece 45 is set to 90 degrees, the bending rigidity of the base 21 is reliably increased in equal directions.

(3) Element Unit of the Second Embodiment

FIG. 6 schematically shows the structure of an element unit 17a of the second embodiment. With this element unit 17a, one segment 61a, 61b, . . . is formed from a group of a plurality of Xrows of elements 23. In the drawing, one segment 61a and 61b is formed from the element 23 group connected in common to three lines of the first conductive

films 29. The vibration films 24 belonging to one segment 61a and 61b vibrate simultaneously according to the supply of drive signals.

The reinforcing body 62 is equipped with a plurality of first elongated pieces (first straight line parts) 63 extending in the Xrow direction of the element array 22 (first direction) between the segments 61a and 61b, a plurality of second elongated pieces (second straight line parts) 64 arranged between adjacent elements 23 in the Xrow direction extending in the column direction of the element array 22 (second direction) within each segment 61a and 61b, and a plurality of third elongated pieces (first straight line parts) 65 arranged between adjacent elements 23 in the column direction extending in the Xrow direction of the element array 22 within each segment 61a and 61b. The first elongated pieces 63 and the third elongated pieces 65 are arranged in parallel to each other. The first elongated pieces 63 and the third elongated pieces 65 have a shape cutting across the area of the element array 22 in the column direction from one end to the other. The reinforcing body 62 has a plurality of crossing parts arranged separated in the column direction for each group of elements 23 connected in common to one signal line. The second elongated pieces 64 are interrupted for each segment 61a and 61b. At the boundary line of the segments 61a and 61b is formed a space 66 between the second elongated pieces 64. In this way, though they cross the third elongated pieces 65, the second elongated pieces 64 are separated by the space from the first elongated pieces 63 in the column direction. In this way, the reinforcing body 43 is segmented in the column direction for each group of elements 23 connected in common to one signal line. Since the reinforcing body 43 is interrupted for each segment 61a and 61b, transmission of ultrasonic vibration between the segments 61a and 61b conveyed through the reinforcing body 43 is prevented. Crosstalk of the ultrasonic waves is reduced.

Here, the first elongated pieces 63 pierce through the space 66 formed between the second elongated pieces 64. An auxiliary reinforcing body 67 extends in the column direction in parallel to the space 66 formed by segmenting of the second elongated pieces 64. The auxiliary reinforcing body 67 is overlapped on the surface of the flexible film 47, the same as the reinforcing body 62. The first elongated pieces 63 cross the auxiliary reinforcing body 67 in a T shape. In this way, the auxiliary reinforcing body 67 is connected to the first elongated pieces 63. As a result, even when the second elongated pieces 64 are segmented, the segmented areas are reinforced by the auxiliary reinforcing body 67. Despite the segmenting of the reinforcing body 62, it is possible to ensure rigidity by the working of the auxiliary reinforcing body 67. In addition, with the element unit 17a of this second embodiment, constitutions other than the constitution noted with the description above is the same as that of the element unit 17 of the first embodiment described above.

In addition, with the element unit 17a, as shown in FIG. 7, for example, it is also possible to further divide each segment 61a and 61b into smaller segments. Here, one segment 61a and 61b can respectively be divided into three small segments F, G, and H. When dividing, a common ground line is established for each two lines of second conductive films 31. In this way, small segments F, G, and H are formed for each group of elements 23 of two columns and three rows. The reinforcing body 62 has a plurality of crossing parts arranged separated in the first direction. The vibration films 24 belonging to each small segment F, G, and H vibrate simultaneously according to the supply of drive

signals. The third elongated pieces **65** of the reinforcing body **62** are segmented for each group of elements **23** of two columns. In this way, the small segments F, G, and H can be arranged in array form.

(4) Element Unit of the Third Embodiment

FIG. 8 schematically shows the structure of an element unit **17b** of the third embodiment. With this element unit **17b**, the film thickness t_s of the second conductive film **41** increases between adjacent piezoelectric films **28**. Between the piezoelectric films **28**, the film thickness t_s of the second conductive film **31** is greater than the film thickness t_f of the first conductive film **29**. Then, a protective conductive film **68** continues on the piezoelectric film **28** from the second conductive film **31** between the piezoelectric films **28**. The protective conductive film **68** is covered on the side surface of the piezoelectric film **28**. In this way, the protective conductive film **68** protects the side surface of the piezoelectric film **28** from dampness, for example.

A space **71** in contact with the piezoelectric film **28** is formed between the first conductive film **29** and the protective conductive film **68** on the piezoelectric film **28**. The space **71** insulates the protective conductive film **68** from the first conductive film **29**. The space **71** is occupied by an insulating film **72**. Therefore, the protective conductive film **68** is separated from the first conductive film **29** by the insulating film **72**. The insulating film **72** continues from the reinforcing body **43** (**62**). Specifically, the insulating film **72** is formed as a single unit on the reinforcing body **43** (**62**).

Here, a separating wall **73** is formed on the reinforcing body **43**. The separating wall **73** is an object having greater acoustic impedance than the acoustic impedance of the acoustic adjustment layer **54**, and is constituted from a solid having a Young's modulus that is greater than the Young's modulus of the acoustic adjustment layer **54**. The separating wall **73** can be formed using a photoresist film hardened by heat, for example.

The acoustic lens **55** has a bonding surface **74** that expands within one plane. The acoustic lens **55** is adhered to the acoustic adjustment layer **54** and the top surface **75** of the separating wall **73** without interruption at the bonding surface **74**. A cavity **76** that is recessed from the bonding surface with the acoustic lens **55** is formed on the top surface **75** of the separating wall **73**. The space inside the cavity **76** is occupied by an adhesive layer **77**. The top surface **75** of the separating wall **73** is bonded to the acoustic lens **55** by the adhesive layer **77**. The adhesive layer **77** is formed using the same material as the acoustic adjustment layer **54**.

The vibration film **24** does ultrasonic vibration with the sending of ultrasonic waves. The ultrasonic vibration is transmitted within the acoustic adjustment layer **54**, and emitted from the interface of the acoustic adjustment layer **54**. The ultrasonic vibration is transmitted across the interface to the acoustic lens **55**. At this time, the separating wall **73** is formed between adjacent elements **23**. An interface is formed on the acoustic adjustment layer **54** between adjacent elements **23** according to the difference in acoustic impedance. The interface prevents transmission of the ultrasonic vibration. As a result, the transmission of ultrasonic vibration from one vibration film **24** that does ultrasonic vibration toward the vibration film **24** of the adjacent element **23** is prevented. Ultrasonic wave crosstalk during ultrasonic vibration of one vibration film **24** is prevented.

The separating wall **73** is constituted using a solid having a Young's modulus greater than the Young's modulus of the acoustic adjustment layer **54**. As a result, the rigidity of the

acoustic adjustment layer **54** is reinforced by the separating wall **73**. Crushing of the acoustic adjustment layer **54** in the thickness direction is prevented. The distance between the vibration film **24** and the interface of the acoustic adjustment layer **54** is kept constant. Ultrasonic waves can be radiated from the interface efficiently. At this time, the acoustic lens **55** is adhered to the surface of the acoustic adjustment layer **54** and the top surface **75** of the separating wall **73** by the bonding surface **74**. Therefore, the acoustic lens **55** is supported by the separating wall **73**. It is possible to reliably prevent crushing of the acoustic adjustment layer **54** in the thickness direction.

The surface of the acoustic adjustment layer **54** has the function of an adhesive agent. As a result, the acoustic lens **55** is adhered to the acoustic adjustment layer **54**. Close adherence is maintained. Though the surface of the acoustic adjustment layers **54** layers is interrupted by the separating wall **73**, the acoustic lens **55** is adhered to the top surface **75** of the separating wall **73** by the work of the adhesive layers **77**. Even when the separating wall **73** is formed, a reduction in the acoustic lens **55** adherence area is kept to a minimum. In fact, when the acoustic lens **55** is bonded to the separating wall **73**, it is possible for the acoustic lens **55** and the separating wall **73** to form a structure. The structure can even more reliably prevent deformation of the acoustic adjustment layer **54**.

The cavity **76** is formed on the top surface **75** of the separating wall **73**. The cavity **76** is occupied by the adhesive layer **77**. The acoustic lens **55** is bonded to the top surface **75** of the separating wall **73** by the adhesive layer **77**. At this time, the acoustic lens **55** is received on the top surface **75** of the separating wall **73**. Therefore, the thickness of the acoustic adjustment layer **54** is determined by the position of the top surface **75** of the separating wall **73**. The thickness of the acoustic adjustment layer **54** can be set with good precision according to the dimensional precision of the separating wall **73**. In fact, the reduction in the adherence area of the acoustic lens **55** is kept to a minimum.

With the element unit **17b**, the adhesive layer **77** is formed using the same material as the acoustic adjustment layer **54**. Therefore, as described later, the adhesive layer **77** can be formed using the same manufacturing process as that of the acoustic adjustment layer **54**. Having the manufacturing process become complex is avoided. Having the manufacturing cost increase is avoided.

Next, a brief description of the method of manufacturing the element unit **17b** will be provided. A substrate **81** is prepared. The substrate **81** is formed from silicon, for example. On the surface of the substrate **81**, for example, a heat treatment is implemented and an oxide film is formed. In this way, the main unit **46** and the silicon oxide layer **51** are formed from the substrate **81**. On the surface of the silicon oxide layer **51**, the zirconium oxide layer **52** is formed on the entire surface. On the surface of the zirconium oxide layer **52**, the first conductive film **29** is formed. Photolithography technology can be used for forming these. Subsequently, the piezoelectric film **28** is formed on the zirconium oxide layer **52**. As shown in FIG. 9, photolithography technology can similarly be used for forming this. The raw material film of the piezoelectric film **28** undergoes etching processing according to the pattern of a resist film. At this time, the first conductive film **29** is cut from the surface at a position separated from the resist film **83**. The film thickness of the first conductive film **29** is reduced. In this way, the film thickness of the first conductive film **29**

becomes smaller than the film thickness of the lower electrode 27. When the etching processing ends, the resist film 83 is removed.

Subsequently, the second conductive film 31 is formed on the zirconium oxide layer 52. As shown in FIG. 10, for formation of the second conductive film 31, a raw material film 84 is formed on the entire surface of the surface of the zirconium oxide layer 52. The raw material film 84 has a uniform film thickness. The raw material film 84 is formed from a conductive material. In this way, the raw material film 84 is covered at least on the exposed surface of the first conductive film 29 and the piezoelectric film 28. The film thickness of the first conductive film 29 increases. A resist film 85 is formed according to the designated pattern on the raw material film 84. For formation of the resist film 85, photolithography technology can be used, for example. The resist film 85 models the shape of the second conductive film 31.

As shown in FIG. 11, etching processing is implemented according to a designated pattern on the raw material film 84. The raw material film 84 is removed at a position separated from the resist film 85. In this way, the second conductive film 31 is formed from the raw material film 84. The outline of the upper electrode 26 is partitioned on the piezoelectric film 28. On the piezoelectric film 28, the protective conductive film 68 is formed separated from the upper electrode 26. The space 71 is formed on the raw material film 84. The protective conductive film 68 and the upper electrode 26 are separated by the space 71. When the etching processing ends, the resist film 85 is removed.

Subsequently, the reinforcing body 43 is formed on the zirconium oxide layer 52. As shown in FIG. 12, for forming the reinforcing body 43, the raw material film 86 is formed on the entire surface of the surface of the zirconium oxide layer 52. The raw material film 86 has a uniform film thickness. The raw material film 86 is formed from an insulating material. The raw material film 86 has a Young's modulus greater than the Young's modulus of the substrate 81. The raw material film 86 is filled into the space 71. The resist film 87 is formed according to a designated pattern on the raw material film 86. For forming of the resist film 87, photolithography technology can be used, for example. The resist film 87 models the shape of the reinforcing body 43.

Etching processing is implemented according to a designated pattern on the raw material film 86. The raw material film 86 is removed at a position separated from the resist film 87. In this way, the reinforcing body 43 (62) is formed from the raw material film 86. When the etching processing ends, the resist film 87 is removed. After that, the acoustic adjustment layer 54 is formed on the surface of the substrate 81. The openings 48 are formed on the back surface of the substrate 81. The vibration film 24 is established. The reinforcing plate 56 is adhered. In this way, the element unit 17b is manufactured.

With the manufacturing method of this embodiment, for formation of the piezoelectric film 28, etching processing was implemented. At this time, the first conductive film 29 is exposed to etching processing in the periphery of the piezoelectric film 28. As a result, the film thickness of the first conductive film 29 is reduced compared to the lower electrode 27. After that, the raw material film 84 is laminated on the first conductive film 29. In this way, the film thickness of the first conductive film 29 increases. It is possible to ensure sufficient film thickness for the wiring film connected to the lower electrode 27. It is possible to avoid an increase in wiring resistance. Therefore, it is possible to sufficiently ensure the ultrasonic wave detection sensitivity.

A detailed description of the embodiments was given as noted above, but a person skilled in the art will easily understand that it is possible to have many modifications without substantially straying from the novel items and effects of the present invention. Therefore, all of these kinds of modification examples are included within the scope of the present invention. For example, for terminology noted at least once together with a different term having a broader or the same meaning in the specification or drawings, that different terminology can be used as a substitute in any location in the specification or drawings. Also, the constitution and operation of the ultrasonic diagnostic device 11, the ultrasonic probe 13, the element units 17, 17a, and 17b, the elements 23, the piezoelectric elements 25 and the like are not limited to the items described with the embodiments, but can also have various modifications.

General Interpretation of Terms

In understanding the scope of the present invention, the term "comprising" and its derivatives, as used herein, are intended to be open ended terms that specify the presence of the stated features, elements, components, groups, integers, and/or steps, but do not exclude the presence of other unstated features, elements, components, groups, integers and/or steps. The foregoing also applies to words having similar meanings such as the terms, "including", "having" and their derivatives. Also, the terms "part," "section," "portion," "member" or "element" when used in the singular can have the dual meaning of a single part or a plurality of parts. Finally, terms of degree such as "substantially", "about" and "approximately" as used herein mean a reasonable amount of deviation of the modified term such that the end result is not significantly changed. For example, these terms can be construed as including a deviation of at least $\pm 5\%$ of the modified term if this deviation would not negate the meaning of the word it modifies.

While only selected embodiments have been chosen to illustrate the present invention, it will be apparent to those skilled in the art from this disclosure that various changes and modifications can be made herein without departing from the scope of the invention as defined in the appended claims. Furthermore, the foregoing descriptions of the embodiments according to the present invention are provided for illustration only, and not for the purpose of limiting the invention as defined by the appended claims and their equivalents.

What is claimed is:

1. A diagnostic ultrasonic device comprising:
 - a base including a partition wall defining a plurality of openings arranged in an array form;
 - a flexible film in contact with a first side of the partition wall and including a plurality of vibration films;
 - a reinforcing plate in contact with a second side of the partition wall;
 - a plurality of ultrasonic transducer elements arranged respectively corresponding to the openings with the vibration films being respectively provided for the ultrasonic transducer elements, each of the ultrasonic transducer elements being constituted by a first conductive film, a piezoelectric film, and a second conductive film; and
 - a reinforcing body fixed to the flexible film in an area between two adjacent vibration films when viewed along a thickness direction of the base, the reinforcing body having Young's modulus greater than Young's

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- modulus of the base, a thickness of the reinforcing body being smaller than a thickness of each of the ultrasonic transducer elements.
2. The ultrasonic device according to claim 1, wherein the reinforcing body, in cooperation with the base, forms a composite body having a second moment of area greater than a second moment of area of the base alone.
 3. The ultrasonic device according to claim 2, wherein the reinforcing body has a crossing part along a first direction and a second direction that cross each other when viewed along the thickness direction of the base.
 4. The ultrasonic device according to claim 3, wherein a crossing angle of the first direction and the second direction is 90 degrees.
 5. The ultrasonic device according to claim 3, wherein when viewed along the thickness direction of the base, the reinforcing body has a first straight line part cutting across an array area of the ultrasonic transducer elements in the first direction.
 6. The ultrasonic device according to claim 3, wherein the reinforcing body has an additional crossing part spaced apart from the crossing part in the second direction for each group of the ultrasonic transducer elements connected in common to one signal line among the ultrasonic transducer elements.
 7. The ultrasonic device according to claim 6, wherein the reinforcing body further includes a first straight line part positioned in an area between the crossing part and the additional crossing part when viewed along the thickness direction of the base, and an auxiliary reinforcing body part extending along the second direction.
 8. The ultrasonic device according to claim 5, wherein the reinforcing body has a second straight line part cutting across the array area of the ultrasonic transducer elements in the second direction when viewed along the thickness direction of the base.
 9. The ultrasonic device according to claim 5, wherein the reinforcing body has an additional crossing part spaced apart from the crossing part in the first direction for each group of the ultrasonic transducer elements connected in common to one signal line among the ultrasonic transducer elements.

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10. The ultrasonic device according to claim 1, further comprising:
 - a first conductive film extending in a first direction in common to the ultrasonic transducer elements;
 - a piezoelectric film disposed on the first conductive film for each of the ultrasonic transducer elements;
 - a second conductive film extending in a second direction in common to the ultrasonic transducer elements; and
 - an insulating film separating the first conductive film from the second conductive film on the piezoelectric film, the insulating film being continuous from the reinforcing body, wherein the reinforcing body is made of an insulating material.
11. The ultrasonic device according to claim 10, further comprising
 - an additional second conductive film extending in the second direction, wherein the first conductive film has a film thickness greater than a film thickness of the second conductive film between the second conductive film and the additional second conductive film.
12. A probe comprising:
 - the ultrasonic device according to claim 1; and
 - a case supporting the ultrasonic device.
13. An electronic equipment comprising:
 - the ultrasonic device according to claim 1; and
 - a processing device connected to the ultrasonic device, and configured to process output of the ultrasonic device.
14. An ultrasonic image device comprising:
 - the ultrasonic device according to claim 1; and
 - a display device configured to display an image generated based on output of the ultrasonic device.
15. The ultrasonic device according to claim 1, wherein the plurality of vibration films are disposed between the plurality of ultrasonic transducer elements and a corresponding opening of the plurality of openings.
16. The ultrasonic device according to claim 1, wherein the reinforcing body is arranged not to overlap the ultrasonic transducer elements when viewed along the thickness direction of the base.

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专利名称(译)	超声波装置，超声波探头，电子设备以及超声波图像装置		
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摘要(译)

一种超声装置，包括基座，多个超声换能器元件和加强体。基座限定以阵列形式布置的多个开口。超声换能器元件分别对应于开口布置，并且分别为超声换能器元件提供多个振动膜。当沿着基座的厚度方向在平面图中观察时，加强体在相邻的振动膜之间的区域中固定到基部。增强体的杨氏模量大于基体的杨氏模量。

